# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6071190

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| **SUBMISSION TYPE:** | NEW ASSIGNMENT |
| **NATURE OF CONVEYANCE:** | ASSIGNMENT |

**CONVEYING PARTY DATA**

| Name | Execution Date |
|---|---|
| MARK I. GARDNER | 03/16/2020 |
| H. JIM FULFORD | 04/18/2020 |
| JEFFREY SMITH | 03/16/2020 |
| LARS LIEBMANN | 03/16/2020 |
| DANIEL CHANEMOUGAME | 03/16/2020 |

**RECEIVING PARTY DATA**

| | |
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| **Name:** | TOKYO ELECTRON LIMITED |
| **Street Address:** | AKASAKA BIZ TOWER, 3-1 AKASAKA 5-CHOME, MINATO-KU |
| **City:** | TOKYO |
| **State/Country:** | JAPAN |
| **Postal Code:** | 107-6325 |

**PROPERTY NUMBERS Total: 1**

| Property Type | Number |
|---|---|
| **Application Number:** | 16854340 |

**CORRESPONDENCE DATA**

**Fax Number:** (703)413-2220

***Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.***

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|---|---|
| **ATTORNEY DOCKET NUMBER:** | 527302US |
| **NAME OF SUBMITTER:** | MATTHEW KORSEN |
| **SIGNATURE:** | /Matthew Korsen/ |
| **DATE SIGNED:** | 04/21/2020 |
| | This document serves as an Oath/Declaration (37 CFR 1.63). |
| **Total Attachments: 12** | |

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# DECLARATION (37 CFR 1.63) AND ASSIGNMENT FOR NONPROVISIONAL UTILITY OR DESIGN PATENT APPLICATION

**Title of Invention**: METHOD FOR FABRICATION OF HIGH DENSITY LOGIC AND MEMORY FOR ADVANCED CIRCUIT ARCHITECTURE

As a below named inventor, I hereby declare that:

This declaration and assignment is directed to:

The attached application having a docket number and title identified above, or United States application number or PCT international application number

________________________ filed on ________________________

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the above-identified application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 C.F.R. § 1.56.

I hereby acknowledge that any willful false statement made in this Declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

**Assignor(s)**: The Assignor(s) is/are the undersigned inventor(s). The inventor(s) named below has/have made certain inventions, improvements, and/or discoveries (herein referred to as the "Invention") disclosed in the above-identified patent application.

**Assignee**: The Assignee is **Tokyo Electron Limited**, a corporation of Japan having a place of business at Tokyo, Japan (herein referred to as the "ASSIGNEE"). The term "ASSIGNEE" used herein includes successors, legal representatives, and assigns of the ASSIGNEE. The ASSIGNEE desires to acquire the entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents obtained from the Invention.

As an undersigned inventor, I hereby assign to the ASSIGNEE my entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefrom in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, I hereby authorize and request the Director of the United States Patent and Trademark Office to issue any United States Patent, granted for the invention, to the ASSIGNEE, and I authorize and request foreign patent authorities to issue any foreign patent, granted for the Invention, to the ASSIGNEE. The entire worldwide right, title, and interest in and to the same to be held and enjoyed by the ASSIGNEE,

to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made. I agree to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, for the ASSIGNEE, whenever requested by the ASSIGNEE.

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(1) Legal name of Inventor: Mark I. GARDNER
Inventor's Signature: Date: 3/16/2020
Residence City/State/Country: Cedar Creek, TX, United States
Mailing Address: c/o NanoFab 300 South, 255 Fuller Road, Suite 214, Albany, NY 12203
Citizenship: United States

(2) Legal name of Inventor: H. Jim FULFORD
Inventor's Signature: Date:
Residence City/State/Country: Marianna, FL, United States
Mailing Address: c/o NanoFab 300 South, 255 Fuller Road, Suite 214, Albany, NY 12203
Citizenship: United States

(3) Legal name of Inventor: Jeffrey SMITH
Inventor's Signature: Date:
Residence City/State/Country: Clifton Park, NY, United States
Mailing Address: c/o NanoFab 300 South, 255 Fuller Road, Suite 214, Albany, NY 12203
Citizenship: United States

(4) Legal name of Inventor: Lars LIEBMANN
Inventor's Signature: Date:
Residence City/State/Country: Mechanicville, NY, United States
Mailing Address: c/o NanoFab 300 South, 255 Fuller Road, Suite 214, Albany, NY 12203
Citizenship: United States

(5) Legal name of Inventor: Daniel CHANEMOUGAME
Inventor's Signature: Date: 03/16/2020
Residence City/State/Country: Niskayuna, NY, United States
Mailing Address: c/o NanoFab 300 South, 255 Fuller Road, Suite 214, Albany, NY 12203
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Mailing Address: c/o NanoFab 300 South, 255 Fuller Road, Suite 214, Albany, NY 12203
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Inventor's Signature: Date: 4/18/2020
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| (4) Legal name of Inventor: | Lars LIEBMANN | | |
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| Residence City/State/Country: | Mechanicville, NY, United States | | |
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| Citizenship: | United States | | |

| | | | |
|---|---|---|---|
| (5) Legal name of Inventor: | Daniel CHANEMOUGAME | | |
| Inventor's Signature: | | Date: | |
| Residence City/State/Country: | Niskayuna, NY, United States | | |
| Mailing Address: | c/o NanoFab 300 South, 255 Fuller Road, Suite 214, Albany, NY 12203 | | |
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Inventor's Signature: Jeffrey T Smith Date: 16 March 2020
Residence City/State/Country: Clifton Park, NY, United States
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